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Product Change Notice (PCN)

Littelfuse, Inc.
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October 1st, 2025

PCN EIC-1160 Additional Epoxy Mold Compound Qualification for POWER SOIC package devices

Detailed Description of Change

Littelfuse IXYS Integrated Circuits Division (ICD) would like to inform you about the qualification of an additional EMC (Epoxy Mold Compound) to ensure security of supply for the part numbers summarized in the table below.

The affected part numbers listed below are fully qualified in accordance with established performance and reliability criteria.

Affected PN list
CPC1907B
CPC1966B
CPC1983B
CPC2907B

Form, fit, function changes: None
Part number changes: None
Replacement products: N/A
Last time buy: N/A
Effective date: November 1st, 2025

The PCN number assigned to this action is **PCN EIC-1160** and must be referenced in any correspondence related to the change.

If you have any other questions or concerns, please contact your local Littelfuse sales representative or Product Manager below for further assistance.

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